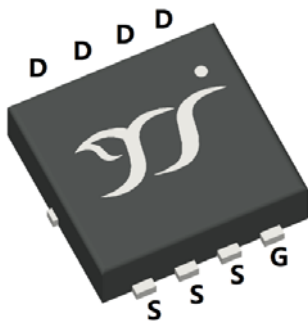
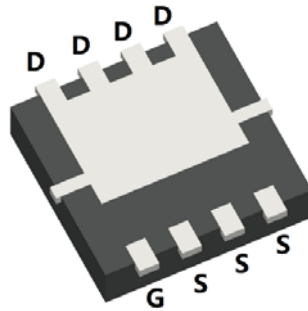


N-Channel Enhancement Mode Field Effect Transistor

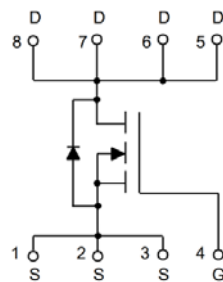


Top View



Bottom View

PDFN3333-8L



Product Summary

- V_{DS} 40V
- I_D 80A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $<5.6m\Omega$
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Split gate trench MOSFET technology
- Low $R_{DS(on)}$ & FOM
- Excellent stability and uniformity
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free
- Part no. with suffix "Q" means AEC-Q101 qualified

Applications

- Power management
- Portable equipment

Parameter	Conditions		Symbol	Min	Max	Unit		
Drain-source Voltage			V_{DS}	-	40	V		
Gate-source Voltage			V_{GS}	-20	20			
Continuous Drain Current (Note 1,2)	Steady-State	$T_A=25^\circ C, V_{GS}=10V$	I_D	-	15	A		
		$T_A=100^\circ C, V_{GS}=10V$		-	10.6			
Continuous Drain Current (Note 1,3)	Steady-State	$T_C=25^\circ C, V_{GS}=10V, \text{Chip limitation}$		-	80			
		$T_C=100^\circ C, V_{GS}=10V$		-	56.5			
Pulsed Drain Current	$T_C=25^\circ C, t_p \leq 10\mu s$			I_{DM}	-		230	
Maximum Body-Diode Continuous Current	$T_C=25^\circ C$			I_S			58	
Avalanche energy (non-repetitive)	$T_J=25^\circ C, V_G=10V, R_G=25\Omega, L=0.5mH, I_{AS}=12.7A$		EAS	-	40.3	mJ		
Total Power Dissipation (Note 1,2)	Steady-State	$T_A=25^\circ C$	P_D	-	2.4	W		
		$T_A=100^\circ C$		-	1.2			
Total Power Dissipation (Note 1,3)	Steady-State	$T_C=25^\circ C$		-	65			
		$T_C=100^\circ C$		-	32			
Junction and Storage Temperature Range				T_J, T_{STG}	-55		175	$^\circ C$

Thermal Resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient (Note 2)	Steady-State	$R_{\theta JA}$	-	63.4	$^\circ C/W$
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	-	2.3	

Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJQ5D6G04HQ	F1	5D6G04H	5000	10000	100000	13" reel



YJQ5D6G04HQ

■ Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A, T_j=25^\circ C$	40	-	-	V
		$V_{GS}=0V, I_D=10mA, T_j=25^\circ C$	40	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=32V, V_{GS}=0V, T_j=25^\circ C$	-	-	1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V, T_j=25^\circ C$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A, T_j=25^\circ C$	2.2	3.0	3.7	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	-	4.5	5.6	m Ω
Diode Forward Voltage	V_{SD}	$I_S=20A, V_{GS}=0V, T_j=25^\circ C$	-	0.83	1.2	V
Gate Resistance	R_G	$f=1MHz, T_j=25^\circ C$	-	1.9	-	Ω
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=20V, V_{GS}=0V, f=1MHz, T_j=25^\circ C$	-	633	-	pF
Output Capacitance	C_{oss}		-	370	-	
Reverse Transfer Capacitance	C_{rfs}		-	19	-	
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=10V, V_{DS}=20V, I_D=20A, T_j=25^\circ C$	-	10.4	-	nC
Gate-Source Charge	Q_{gs}		-	3.4	-	
Gate-Drain Charge	Q_{gd}		-	3.2	-	
Reverse Recovery Charge	Q_{rr}	$I_F=20A, di/dt=100A/\mu s, V_{GS}=0V, V_R=20V, T_j=25^\circ C$	-	8	-	nC
Reverse Recovery Time	t_{rr}		-	17.5	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DS}=20V, I_D=20A, R_{GEN}=3\Omega, T_j=25^\circ C$	-	8.4	-	ns
Turn-on Rise Time	t_r		-	4.2	-	
Turn-off Delay Time	$t_{D(off)}$		-	12.6	-	
Turn-off Fall Time	t_f		-	4.6	-	

Note:

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
2. The value of $R_{\theta JA}$ is measured with the device mounted on the 40mm*40mm*1.1mm single layer FR-4 PCB board with 1 in² pad of 2oz. Copper, in the still air environment with $T_A=25^\circ C$. The maximum allowed junction temperature of 175 $^\circ C$. The value in any given application depends on the user's specific board design.
3. Thermal resistance from junction to soldering point (on the exposed drain pad).



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Typical Electrical and Thermal Characteristics Diagrams

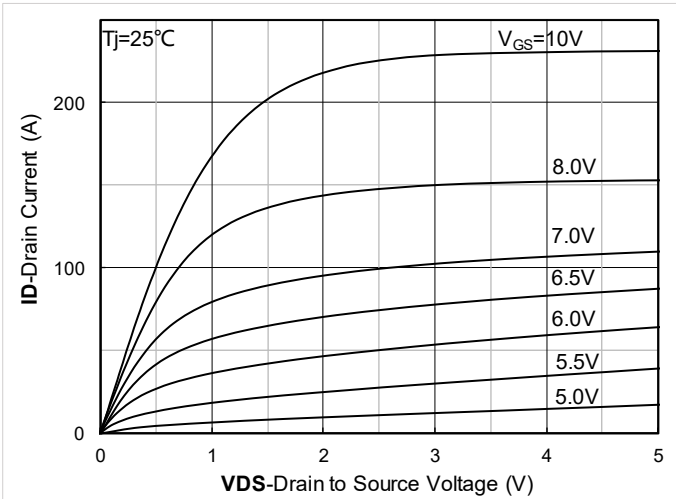


Figure 1. Output Characteristics; typical values

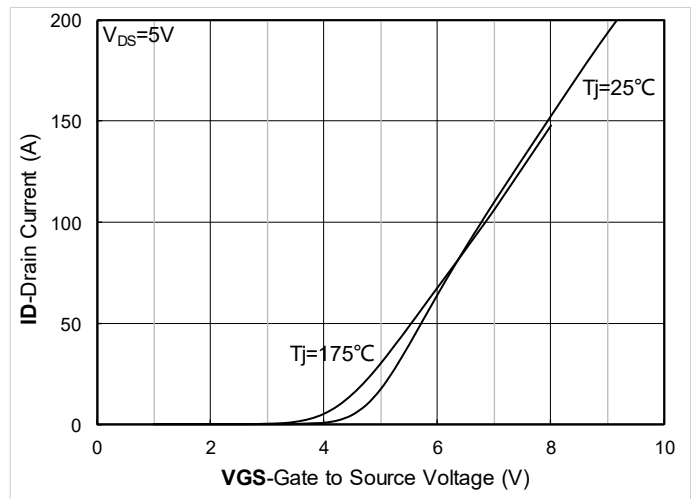


Figure 2. Transfer Characteristics; typical values

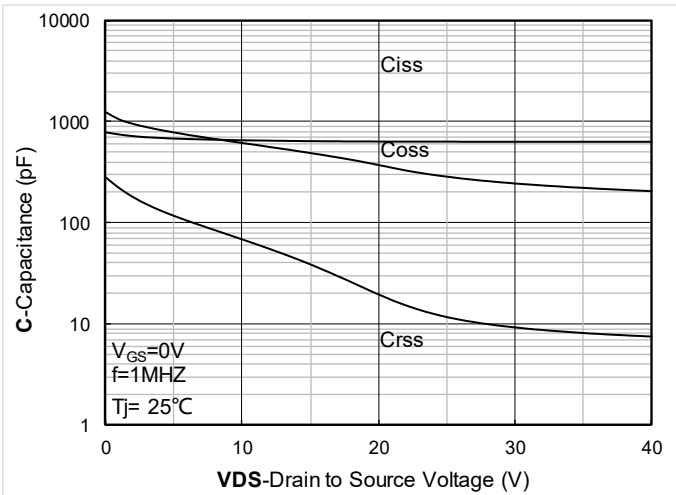


Figure 3. Capacitance Characteristics; typical values

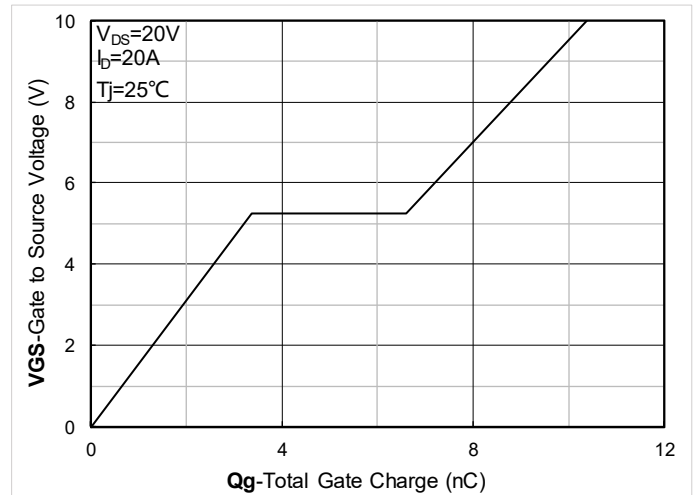


Figure 4. Gate Charge; typical values

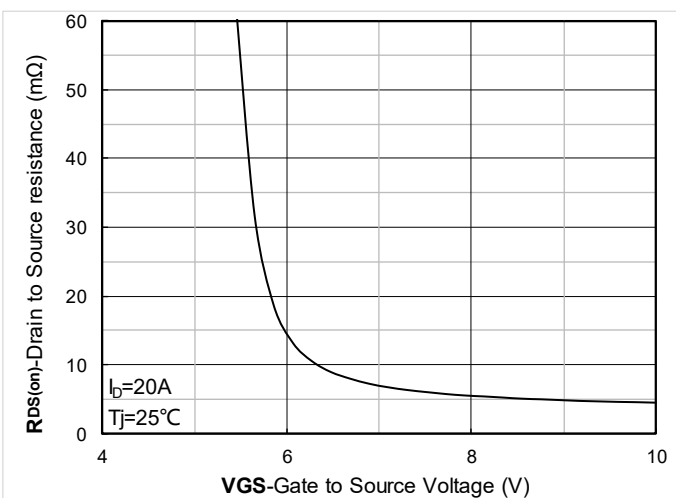


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

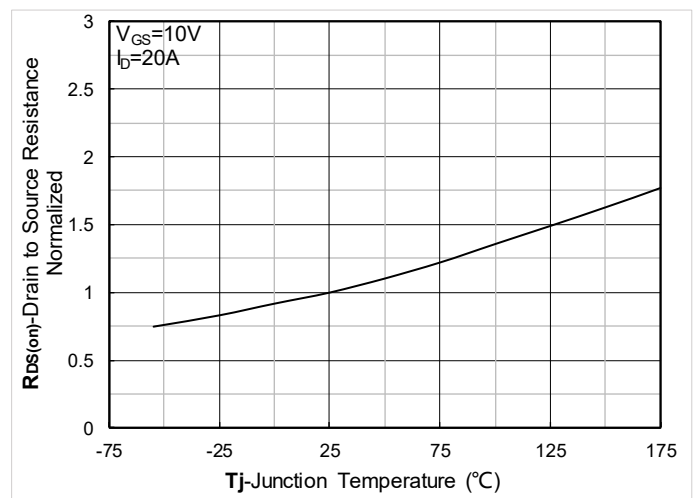


Figure 6. Normalized On-Resistance



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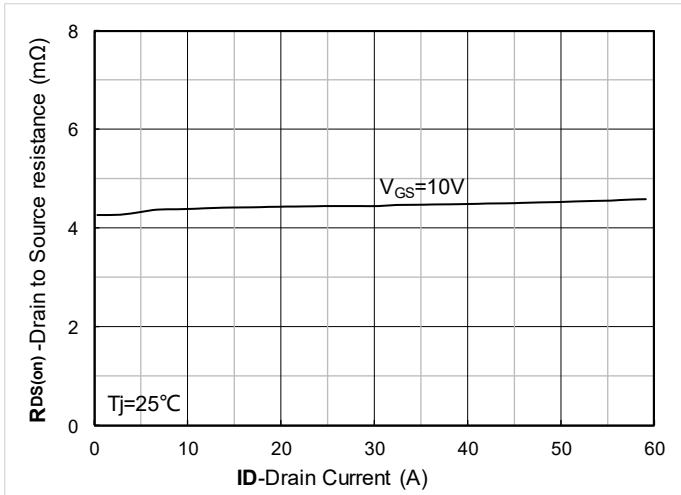


Figure 7. RDS(on) vs. Drain Current; typical values

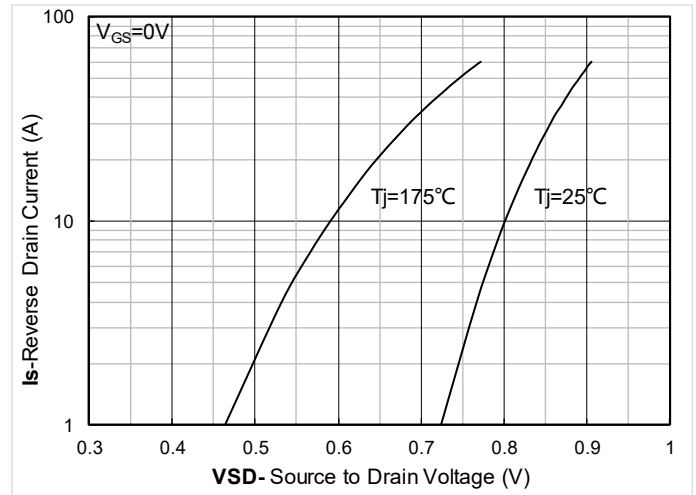


Figure 8. Forward characteristics of reverse diode; typical values

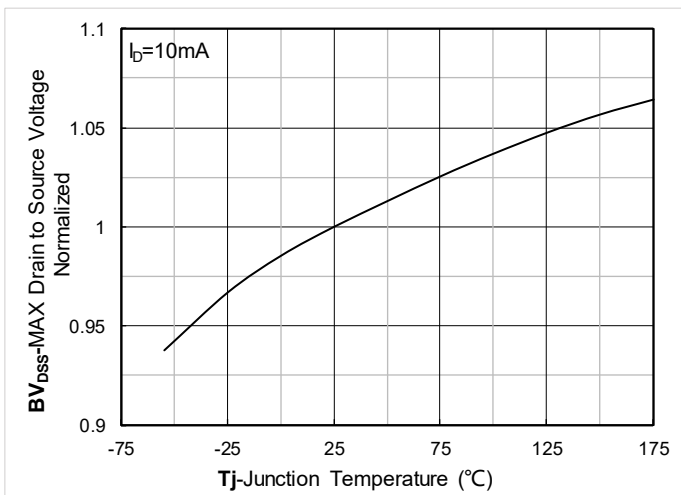


Figure 9. Normalized breakdown voltage

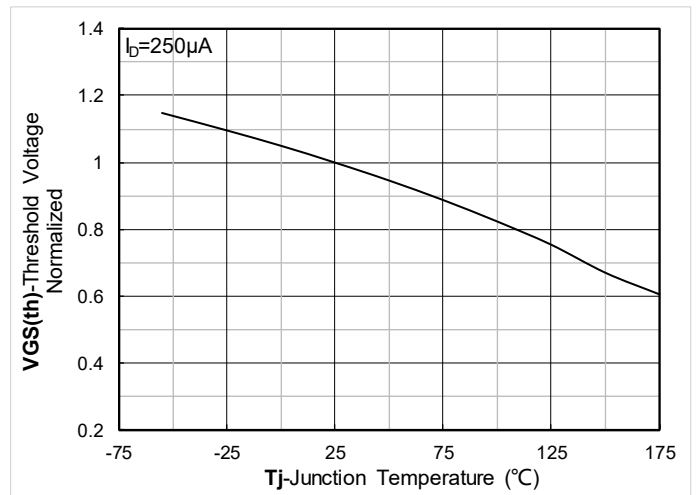


Figure 10. Normalized Threshold voltage

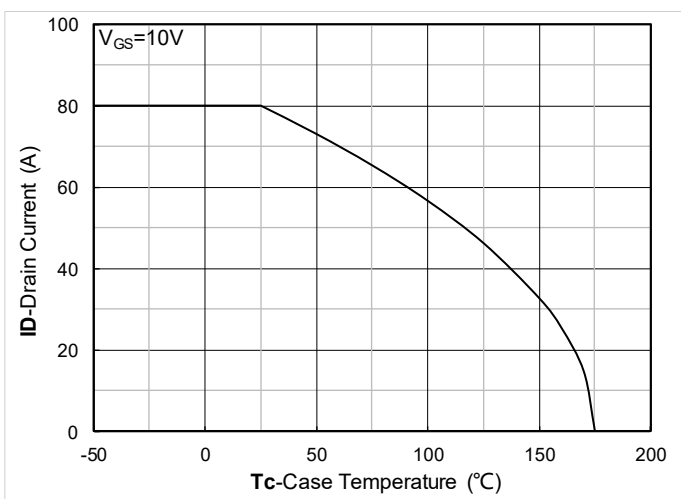


Figure 11. Current dissipation

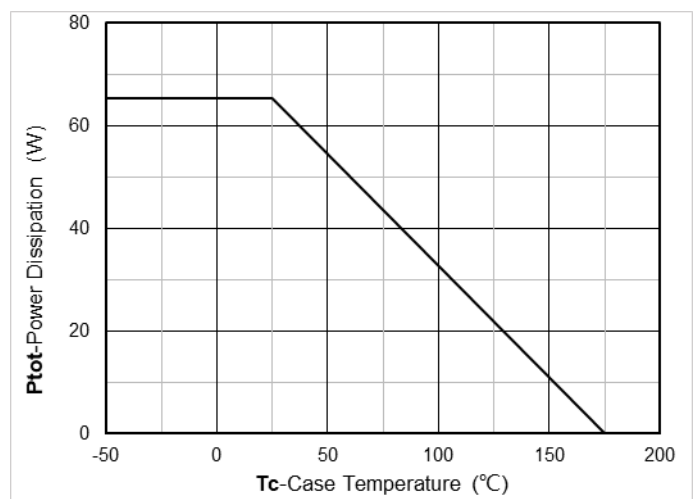


Figure 12. Power dissipation



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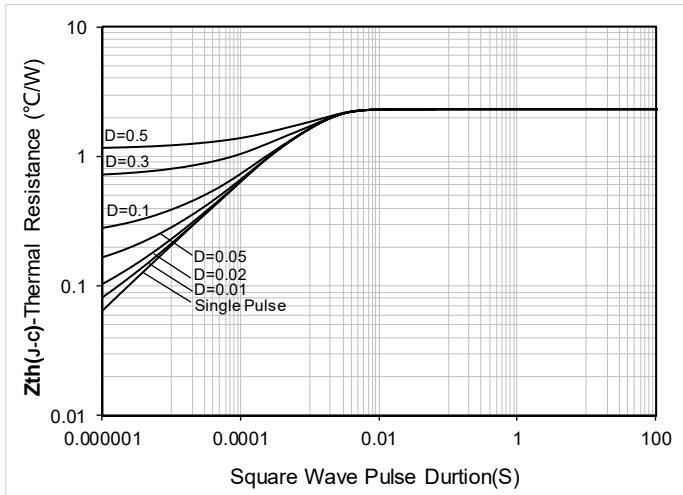


Figure 13. Maximum Transient Thermal Impedance

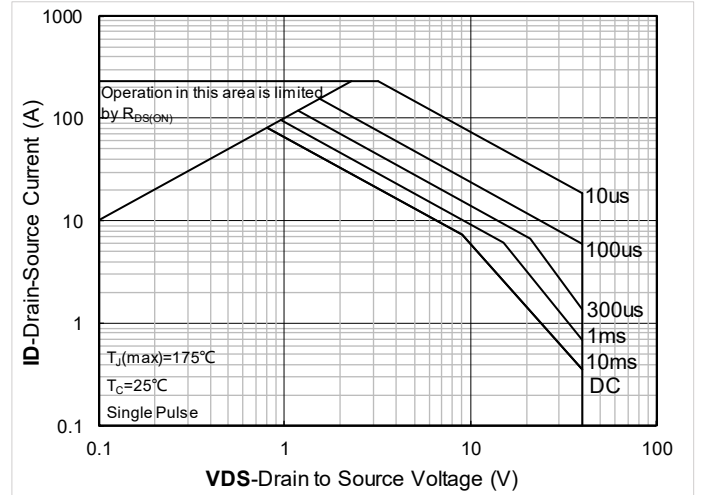


Figure 14. Safe Operation Area

■ Test Circuits & Waveforms

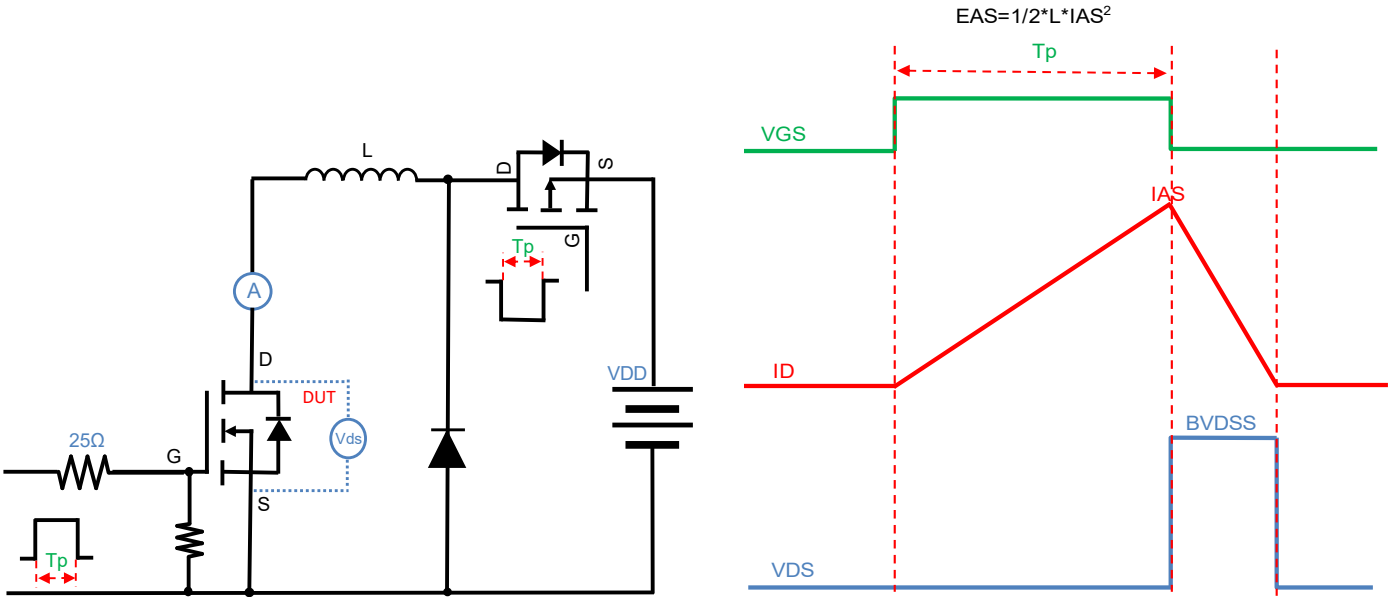


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

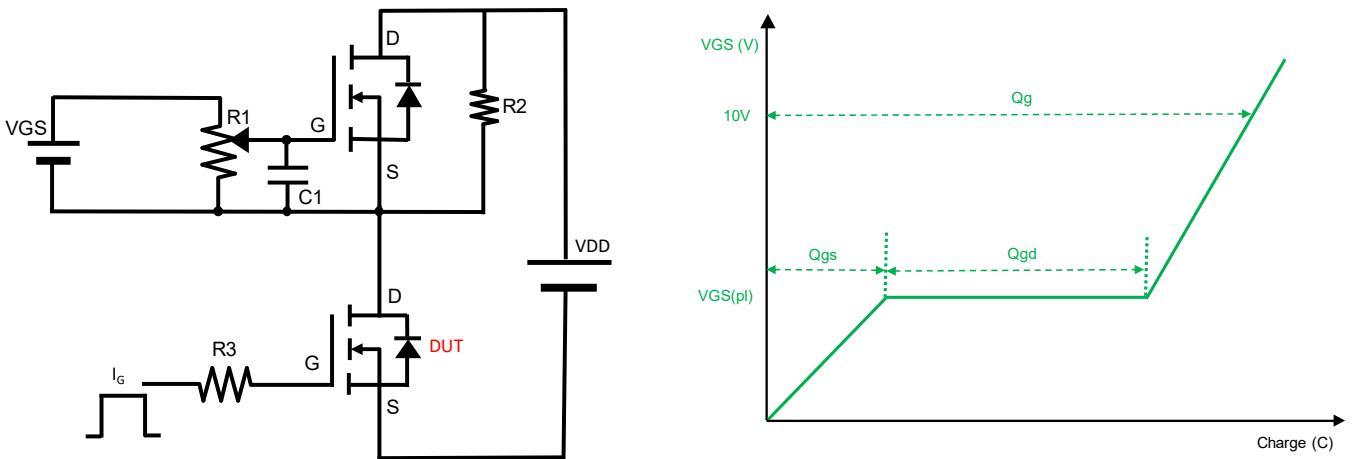


Figure B. Gate Charge Test Circuit & Waveform

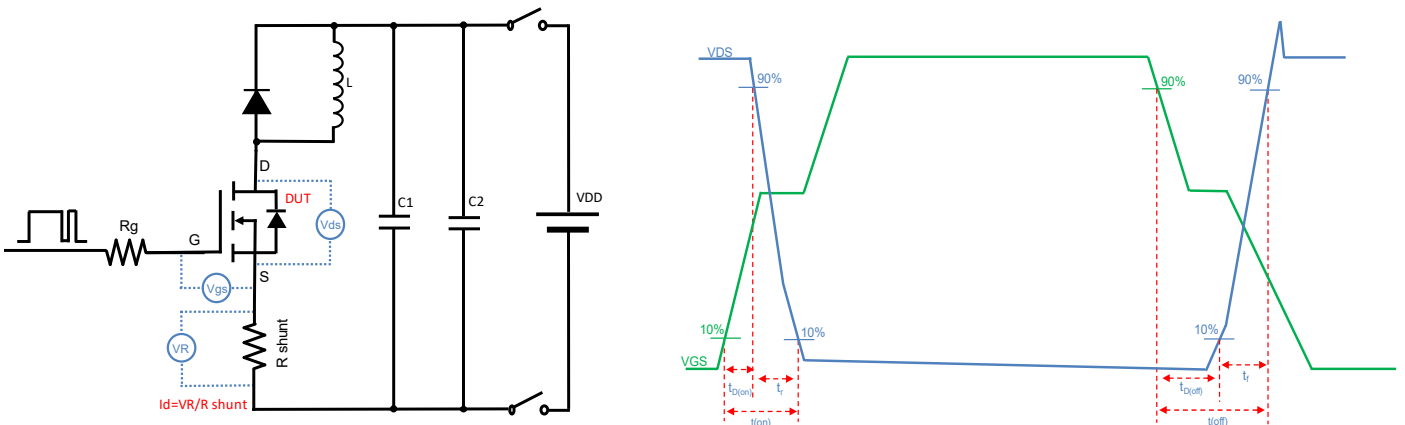


Figure C. Resistive Switching Test Circuit & Waveform

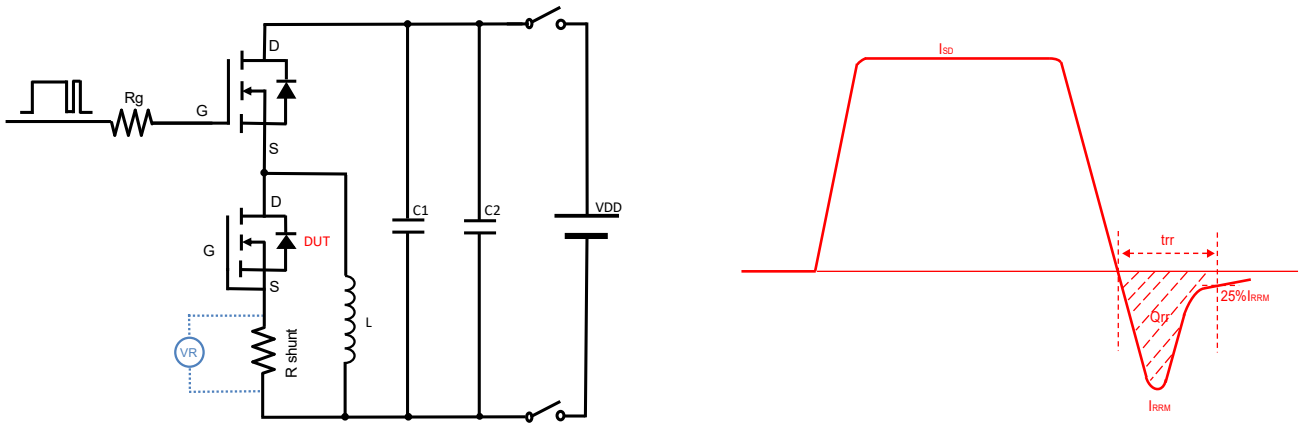
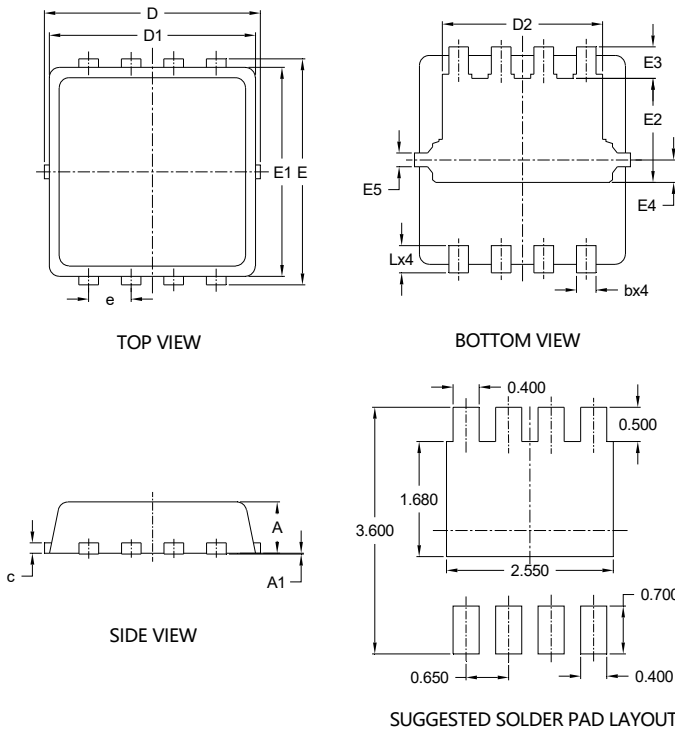


Figure D. Diode Recovery Test Circuit & Waveform



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■ PDFN3333-8L-B-0.75mm Package information



SYMBOL	DIMENSIONS			
	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.028	0.033	0.700	0.850
A1	0.000	0.002	0.000	0.050
b	0.008	0.016	0.200	0.400
c	0.004	0.010	0.100	0.250
D	0.124	0.136	3.150	3.450
D1	0.118	0.130	3.000	3.300
D2	0.089	0.104	2.250	2.650
E	0.124	0.136	3.150	3.450
E1	0.114	0.126	2.900	3.200
E2	0.052	0.068	1.320	1.720
E3	0.011	0.026	0.280	0.650
E4	0.013 REF		0.330 REF	
E5	0.008 REF		0.200 REF	
e	0.026 BSC		0.650 BSC	
L	0.012	0.020	0.300	0.500

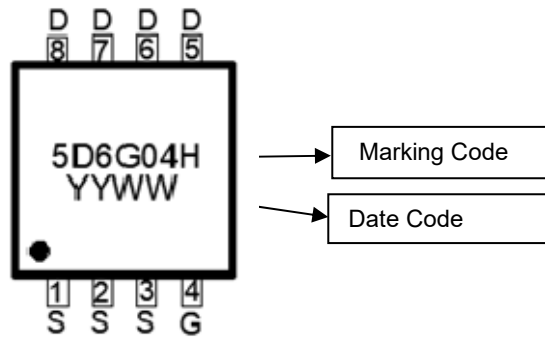
NOTE:
 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
 2. TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
 3. THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

UNIT: mm



YJQ5D6G04HQ

■ Marking Information



Note:

1. All marking is at middle of the product body
2. All marking is in laser printing
3. 5D6G04H is Marking Code, YYWW is date code, "YY" is year, "WW" is week
4. Body color: Black



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